

H1001 – Technical Data Sheet



Bondrite Adhesives Limited
Unit 3H
Sileby Road Industrial Estate
Barrow-Upon-Soar
Leicestershire LE12 8LP
Tel: 01509 815550

Description

H1001 is an outstanding high performance clear hot melt adhesive, specifically designed product assembly, and packaging operations.

H1001 is translucent / tan in appearance, flexible, with good flow characteristics and high / aggressive tack.

Typical Uses

Typical uses for H1001 include:

- Packaging applications,
- Printing and print finishing,
- Furniture,
- Product assembly markets.

H1001 has been found suitable for bonding materials such as paper & board, timber, hardboard, foams, ABS, Perspex, aluminium, and other porous and non-porous materials.

Physical Properties

Base	EVA copolymer
Colour	Translucent / tan
Viscosity @200°C in poise	30 poise Brookfield RVT Thermosel
Softening Point in °C	102°C (Ring & Ball)
Heat Resistance	-40 to +70°C
Working Temp in °C	180-215
Open time	15-45 seconds (depending on amount applied and application temperature)
Max storage temp	30°C

Precautions

H1001 is acceptable under Section 175.105 of the USA FDA regulations for use as a food packaging adhesive.

Fumes should not be inhaled. Use in a well ventilated area.

Avoid ingestion. If ingestion occurs, seek medical advice.

Please consult the H1001 Health & Safety Data Sheet for statutory regulation information.

Information relating to the products of Bondrite Adhesive Limited is based on tests carried out under laboratory conditions. If any of our products are not used in accordance with our instructions or are used under conditions which vary from our laboratory, they may not perform in accordance with any information provided and Bondrite shall not have any liability in this case. Bondrite will accordingly provide samples of our products, on request and free of charge, for Customers to carry out their own tests as to suitability of our product for their purposes and as used in their intended environment.

Purchase from Bondrite

Issue Date – November 2021